



System-On-Modules


Our Reliable and Scalable SOMs for Your Embedded Solutions





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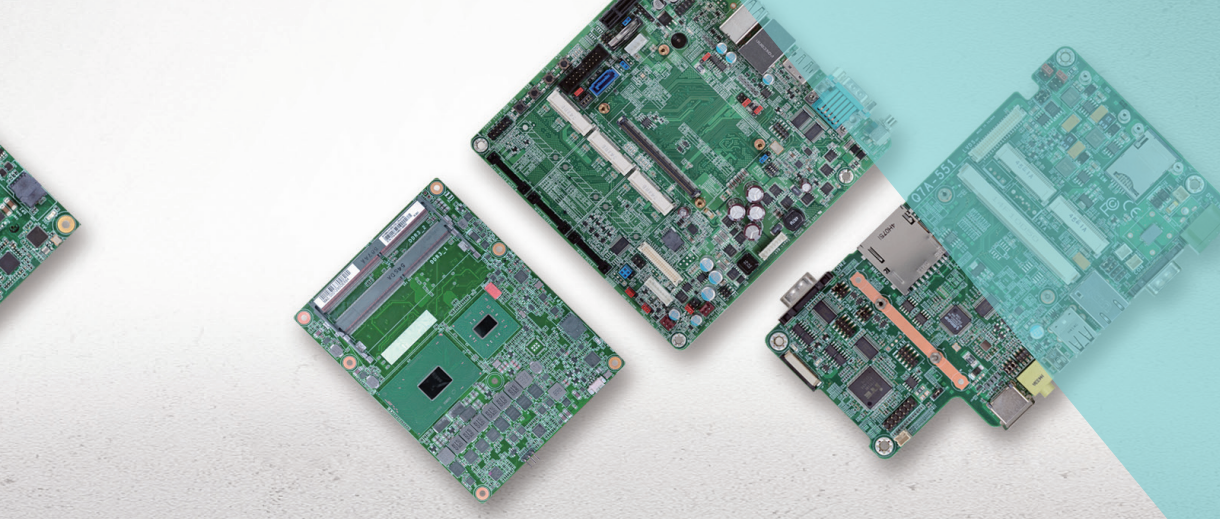
We provide off-the-shelf System-On-Modules including COM Express Mini, COM Express Compact, COM Express Basic, Qseven, SMARC and Customized Design-in Services for various embedded computing solutions

System-On-Modules Product Overview

Qseven	Processor	Platform	Chipset	Model	Index
 <p>RK701</p>	Rockchip RK3568 / RK3568J Cortex A55	ARM	-	RK701	P6
	Intel® Atom® Processor x6000	Atom	-	EHL701 EHL700	
	Intel® Atom® Processor E3900	Atom	-	AL701 AL700	P7
	Intel® Atom® Processor E3800	Atom	-	BT700	
	Freescaler™ i.MX6 Series	ARM	-	FS700	

COM Express Mini	Type	Processor	Platform	Chipset	Model	Index
 <p>ASL9A2</p>	Type 10	11th Gen Intel® Core™ Processor	ULT	-	TGU9A2	P8
		8th Gen Intel® Core™ Processor	ULT	-	WL9A3	
		Intel® Atom® Processor Amston Lake/ Alder Lake-N Series	Atom	-	ASL9A2	
		Intel® Atom® Processor Elkhart Lake Series	Atom	-	EHL9A2	
	Intel® Atom® Processor E3900/ Intel® Pentium® N4200	Atom	-	AL9A2 AL9A3 AL9A8	P9	
	Intel® Atom® Processor E3800	Atom	-	BT9A3		
	AMD® Ryzen™ R1000 Series Processor	AMD	-	GH9A3		

COM Express Compact	Type	Processor	Platform	Chipset	Model	Index
 <p>MTH968</p>	Type 6	14th Gen Intel® Core™ Processor	ULT	-	MTH968	P10
		13th Gen Intel® Core™ Processor	ULT	-	RPP968	
		12th Gen Intel® Core™ Processor	ULT	-	ADP968	
	11th Gen Intel® Core™ Processor	ULT	-	TGU968	P11	
	8th Gen Intel® Core™ Processor	ULT	-	WL968		
	7th Gen Intel® Core™ Processor	ULT	-	KU968		
	6th Gen Intel® Core™ Processor	ULT	-	SU968		
	Intel® Atom® Processor E3900/ Intel® Pentium® N4200	Atom	-	AL968		
	Intel® Atom® Processor E3800	Atom	-	BT968		



COM Express Basic



RBT970

Type	Processor	Platform	Chipset	Model	Index
Type 7	AMD® Ryzen™ Embedded V3000 Series processors	AMD	-	RBT970	P12
	3rd Gen Intel® Xeon® Scalable Processors D-1700 Family	Server	-	ICD970	
	Intel® Atom® Processor C3000	Atom	-	DV970	
Type 6	11th Gen Intel® Core™ Processor	Mobile	RM590E/ QM580E/ HM570E	TGH960	P13
	9th/8th Gen Intel® Core™ Processor	Mobile	CM246	CH960-CM246/QM370	
			QM370	CH961-CM246/QM370	
			HM370	CH960-HM370 CH961-HM370	
	6th Gen Intel® Core™ Processor	Mobile	CM236/ QM170	SH960MD-CM236/ QM170	
AMD® Ryzen™ V1000/R1000 Embedded Processors	AMD	-	GH960		

COM HPC



RPS9HC-R680E /
Q670E / H610E

Processor	Platform	Chipset	Model	Index
13th Gen Intel® Core Processors	Desktop	R680E/ Q670E/ H610E	RPS9HC-R680E/ Q670E/H610E	P14

Carrier Board



COM100-B

Type	Form Factor	Compliance	Model	Index
Type 10	Mini-ITX	COM Express R2.1	COM100-B	P15
Type 6, Type 10	microATX	COM Express R3.1	COM335	
Type 7		COM Express R3.0	COM333-I	
Type 6		COM Express R2.1	COM332-B(R.A)	
Type 6		COM Express R2.1	COM332-B(R.B1)	P16
-	Mini-ITX	Qseven (BT700)	Q7X-151(R.A)	
-		Qseven (AL700, AL701, BT701)	Q7X-151(R.D1)	
-	Proprietary	Qseven (FS700)	Q7A-551	

SDM



SDML-WL

Form Factor	Compliance	Model	Index
SDM Large	Intel® Smart Display Module	SDML-WL	P17

Design Assistance

- Comprehensive evaluation of carrier board design during planning phase
Hardware/Software Recommendations, Technical Specifications, Developing Schedule, and Database Schematic Review, Placement/Layout Review, Debugging Assistance Services, and General/Special Reference Design
- Comprehensive design documentation for designing carrier board
Carrier Board Design Guide, User's Manual, Schematic & Layout Checklist, and 2D/3D Mechanical Drawing

Strict Validation

- Strict validation and testing process ensures reliable deployments
Dedicated Design Review Team, Thermal Simulation, and COMe Debug Module Card

Thermal Solution

- Customized thermal solution design & Optional heatspreader
For special requirements like high-temperature environments or ultra-slim chassis

Software Integration

- Embedded OS and BIOS customization
Windows 10, Windows 7, WES 7, Windows XP, Linux (CentOS/Debian), etc.
- Windows licensing offerings
- Application Programming Interface (API) library
Watchdog, Hardware Control/Monitor, GPIO, Backlight Control, SMBus, etc.
- Remote management utility



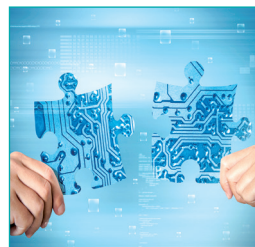
Planning



Design



Validation



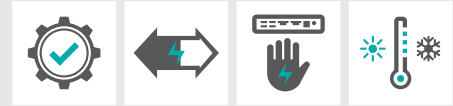
Integration



Production

Rugged Design

- Industrial-rated components with high MTBF over 100,000 hrs
- Extended operating temperatures
- High ESD protection for I/O ports
- Signal integrity measurement
- Wide range power design
- 100% Japanese-made solid capacitor
- Power hot plug protection for DC-in type SBC and Industrial Motherboards



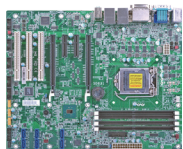
Software Integration

- Embedded BIOS and OS customization services
- Windows licensing offerings
- Android, Linux distribution (Yocto/Ubuntu/CentOS/Debian)
- Embedded API
(Hardware Monitor, SMBus, I²C, Brightness Control, GPIO, Watchdog)
- Remote management utility



Embedded Total Solution

- Express customization service: 30 days (NRE cost: project based)
- Strict revision control
- Long product life cycle support
- High volume OEM/ODM production capabilities



Embedded Boards



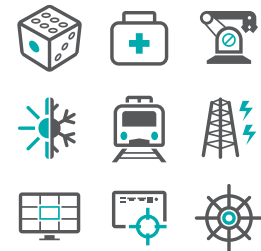
Peripherals



Systems



Embedded Software & BIOS



Vertical Solutions

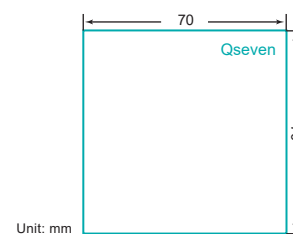
Qseven

Extremely Small & Mobile Solutions



Features

Qseven is equipped with fast serial interfaces in an ultra-small form factor with a measurement of just 70 x 70 mm. It is much smaller than other system-on-module standards such as COM Express, which makes it an ideal solution for space-limited and low power applications such as industrial automation, retail, and power & energy.



Wide Temp



ARM

Wide Temp



Atom

Wide Temp



Atom

Model Name		RK701	EHL701	EHL700
Compliance		Qseven R2.1	Qseven R2.1	Qseven R2.1
System	Processor	Rockchip RK3568 / RK3568J Cortex A55	Intel Atom® x6000	Intel Atom® x6000
	Socket	FCBGA	BGA 1493	BGA 1493
	Max. Speed	1.8~2GHz	1.2~3.0GHz	1.2~3.0GHz
	TDP	5W	6W/6.5W/9W/10W/12W	6W/6.5W/9W/10W/12W
	Cache	32KB	1M~2M	1M~2M
BIOS		-	AMI SPI 256Mbit (supports UEFI boot only)	AMI SPI 256Mbit (supports UEFI boot only)
Memory	Technology	DDR4 3200MHZ	Dual Channel LPDDR4 3200MHZ	Dual Channel LPDDR4 3200MHZ
	Max. Capacity	2GB / 4GB / 8GB	4GB / 8GB / 16GB	4GB / 8GB
	Socket	Memory Down	Memory down	Memory down
Graphics	Interface	1 eDP/LVDS, 1 DP/TMDS	1 LVDS/eDP, 1 DDI	1 eDP, 1 DDI
Expansion	PCIe	2 PCIe x1 (Gen 3), 1 PCIe x1 (Gen 2)	4 PCIe x1	4 PCIe x1
	LPC	-	1	1
	I ² C	1	1	1
	SMBus	-	1	1
	CAN Bus	1	-	-
Audio	Interface	HD Audio	HD Audio	HD Audio
Ethernet	Controller	1 RTL8211F-CG	1 Intel® I211	1 Intel® I211/I210
I/O	USB	1 USB 3.0, 4 USB 2.0	1 USB 3.1 + 8 USB 2.0 / 2 USB 3.1 + 6 USB 2.0	1 USB 3.2 + 8 USB 2.0 / 2 USB 3.2 + 6 USB 2.0
	SATA	2 SATA 3.0	2 SATA 3.0	2 SATA 3.0
	eMMC	1 eMMC 5.1 up to 128GB (Opt.)	1 eMMC 5.1 up to 128GB (Opt.)	1 eMMC 5.1 up to 128GB (Opt.)
	DIO	4-bit DIO	4-bit DIO	4-bit DIO
	SD	-	-	-
TPM		TPM 2.0	dTPM or fTPM (Opt.)	fTPM
Power		5V, 5VSB, VCC-RTC	5V, 5VSB, VCC-RTC	5V, 5VSB, VCC-RTC
Operating Temperature		-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C, -5°C~65°C (Opt.)	-40°C~85°C, 0°C~60°C, -5°C~65°C (Opt.)

*Populated by default



Wide Temp

Atom

Wide Temp



Atom

Model Name		AL701	AL700
Compliance		Qseven R2.1	Qseven R2.1
System	Processor	Intel® Atom® E3900	Intel® Atom® E3900
	Socket	BGA 1296	BGA 1296
	Max. Speed	1.8~2.5GHz	1.8~2.5GHz
	TDP	6W/6.5W/9.5W/12W	6W/6.5W/9.5W/12W
	Cache	2M	2M
BIOS		AMI SPI 128Mbit (supports UEFI boot only)	AMI SPI 128Mbit (supports UEFI boot only)
Technology		Dual Channel LPDDR4 3200MHz	Dual Channel DDR3L 1600MHz
Memory	Max. Capacity	4GB/8GB	4GB/8GB
	Socket	Memory down	Memory down
Graphics	Interface	1 LVDS*/eDP, 1 DDI	1 LVDS*/eDP, 1 DDI
Expansion	PCIe	4 PCIe x1	4 PCIe x1
	LPC	1	1
	I ² C	1	1
	SMBus	1	1
	CAN Bus	1 (only Linux support)	-
Audio	Interface	HD Audio	HD Audio
Ethernet	Controller	1 Intel® I211AT / 1 Intel® I210IT	1 Intel® I211AT / 1 Intel® I210IT
I/O	USB	1 USB 3.2 + 8 USB 2.0 / 3 USB 3.2 + 4 USB 2.0 (Opt.)	1 USB 3.2 + 8 USB 2.0 / 3 USB 3.2 + 4 USB 2.0 (Opt.)
	SATA	2 SATA 3.0	2 SATA 3.0
	eMMC	eMMC 5.0 up to 32GB (Opt.)	eMMC 5.0 up to 32GB (Opt.)
	DIO	4-bit DIO	4-bit DIO
	SD	Optional	Optional
TPM		fTPM	fTPM
Power		VCC-RTC, 5V standby, 5V	VCC-RTC, 5V standby, 5V
Operating Temperature		-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C

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Wide Temp

Atom



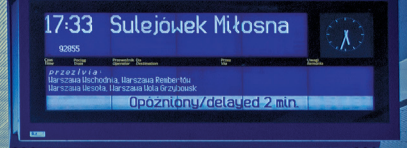
ARM

Model Name		BT700	FS700
Compliance		Qseven R2.0	Qseven R1.2
System	Processor	Intel® Atom® E3800	Freescale™ i.MX6 Series
	Socket	BGA 1170	FCPBGA
	Max. Speed	1.46~2.41GHz	1.0GHz
	TDP	5W/7.5W/8W/10W	-
	Cache	0.5M/1M/2M	32KB
BIOS		AMI SPI 64Mbit	-
Technology		Single Channel DDR3L 1066/1333MHz	Single Channel DDR3 1000/1200MHz
Memory	Max. Capacity	2GB/4GB	1GB/2GB
	Socket	Memory down	Memory down
Graphics	Interface	1 LVDS, 1 DDI	1 HDMI, 2 LVDS
Expansion	PCIe	3 PCIe x1	1 PCIe x1
	LPC	1	-
	I ² C	1	2
	SMBus	1	-
	CAN Bus	-	1
Audio	Interface	HD Audio	I2S
Ethernet	Controller	1 Intel® I211 / 1 Intel® I210	1 Atheros AR8033
I/O	USB	1 USB 3.2, 6 USB 2.0	4 USB 2.0, 1 USB OTG
	SATA	2 SATA 2.0	1 SATA 2.0
	eMMC	1 x 8GB/16GB/32GB eMMC (Opt.)	1 x 4GB*/8GB/16GB eMMC
	DIO	-	1 SDIO
	SD	Optional	1 microSD onboard
TPM		Optional	-
Power		VCC-RTC, 5V standby, 5V	VCC-RTC, 5V standby, 5V
Operating Temperature		-40°C~85°C, -20°C~70°C, 0°C~60°C	-20°C~70°C

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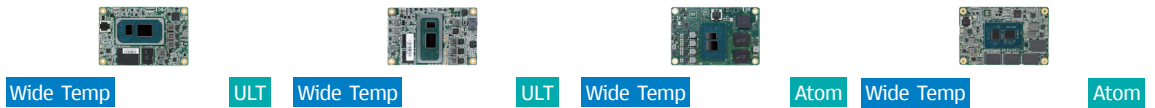
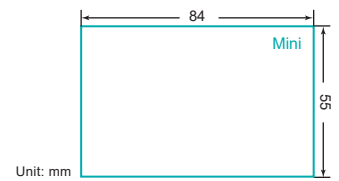
COM Express Mini

Power-Saving & Small-Size Solutions



Features

COM Express® Mini module delivers high performance on a small footprint which features 55 x 84 mm in size. It is ideal for space-limited, power-saving and mobile applications. DFI's ultra-small modules are available with COM Express® pin-out Type 10.



Model Name	TGU9A2	WL9A3	ASL9A2	EHL9A2	
Compliance	COM Express® R3.0 Mini, Type 10	COM Express® R3.0 Mini, Type 10	COM Express® R3.1 Mini, Type 10	COM Express® R3.0 Mini, Type 10	
System	Processor	11th Gen Intel® Core™	8th Gen Intel® Core™	Intel® Atom® Processor Amston Lake Alder Lake-N Series	
	Socket	BGA1526	FCBGA 1528	BGA 1264	
	Max. Speed	up to 3.0GHz(Turbo)	3.9~4.4GHz	3.2~3.8GHz	1.7~4.4GHz
	TDP	15W	15W	6W/9W/10W/12W/15W	6W/9W/10W/12W
	Cache	4M/6M/8M/12M	4M/6M/8M	6M	4M/6M/8M
BIOS	AMI SPI 256Mbit	AMI SPI 128Mbit	AMI SPI 256Mbit	AMI SPI 256Mbit	
Memory	Technology	Single Channel LPDDR4X 4266MHz	Dual Channel LPDDR3 2133MHz	Dual Channel LPDDR5 4800MHz	
	Max. Capacity	8GB/16GB	8GB/16GB	16GB	8GB/16GB
	Socket	Memory down	Memory down	Memory down	-
Graphics	Interface	1 eDP, 1 DDI	1 LVDS*/eDP, 1 DDI	1 LVDS*/eDP, 1 DDI	
Expansion	PCIe	4 PCIe x1	4 PCIe x1	4 PCIe x1	
	SDIO	-	1	-	
	LPC	-	1	1	
	I ² C	1	2	1	
	SMBus	1	1	1	
	CAN Bus	-	-	-	
Audio	Interface	HD Audio	HD Audio	HD Audio	
Ethernet	Controller	1 Intel® I225IT	1 Intel® I219	1 Intel® I226IT/LM	
I/O	USB	2 USB 3.2, 8 USB 2.0	2 USB 3.2, 8 USB 2.0	2 USB 3.2 Gen2, 8 USB 2.0	
	SATA	2 SATA 3.0	2 SATA 3.0	2 SATA 3.0	
	SSD	1 x 64GB/128GB/256GB/512GB/1024GB on board SSD (Opt.)	-	-	
	eMMC	-	1 4GB/8GB/16GB/32GB/64GB eMMC (Opt.)	1 eMMC 5.1 8GB/16GB/32GB/64GB/128GB (Opt.)	
	DIO	8-bit DIO	8-bit DIO	8-bit DIO	
	SD	-	Optional	-	
TPM	dTPM or fTPM (Opt.)	fTPM	dTPM or fTPM (Opt.)	dTPM or fTPM (Opt.)	
Power	4.75V~20V, 5VSB, VCC-RTC (ATX mode), 4.75V~20V, VCC-RTC (AT mode)	12V~20V, 5VSB, VCC-RTC (ATX mode) 12V~20V, VCC-RTC (AT mode)	4.75V~20V, 5VSB, VCC-RTC (ATX mode) 4.75V~20V, VCC-RTC (AT mode)	4.75V~20V, 5VSB, VCC-RTC (ATX mode) 4.75V~20V, VCC-RTC (AT mode)	
Operating Temperature	-40°C~85°C, -5°C~65°C	-30°C~85°C, 0°C~60°C	-40°C~85°C, -5°C~65°C	-40°C~85°C, -5°C~65°C	

*Populated by default



Wide Temp

Atom

Wide Temp



Atom

Wide Temp



Atom

Model Name		AL9A2	AL9A3	AL9A8
Compliance		COM Express® R2.1 Mini, Type 10		COM Express® R3.0 Mini, Type 10
System	Processor	Intel® Atom® E3900 / Intel® Pentium® N4200		Intel® Atom® E3900 / Intel® Pentium® N4200
	Socket	BGA 1296		BGA 1296
	Max. Speed	1.8~2.5GHz		1.8~2.5GHz
	TDP	6W/6.5W/9.5W/12W		6W/6.5W/9.5W/12W
	Cache	2M		2M
	BIOS	AMI SPI 128Mbit (supports UEFI boot only)		AMI SPI 128Mbit (supports UEFI boot only)
Memory	Technology	Single Channel DDR3L 1600MHz	Dual Channel DDR3L 1600MHz	Dual Channel LPDDR4 2400MHz
	Max. Capacity	4GB non-ECC / 8GB ECC	4GB / 8GB	4GB / 8GB
	Socket	Memory down		Memory down
Graphics	Interface	1 LVDS* <i>eDP</i> , 1 DDI	1 LVDS* <i>eDP</i> , 1 DDI	1 LVDS* <i>eDP</i> , 1 DDI
Expansion	PCIe	4 PCIe x1		4 PCIe x1
	SDIO	1 (Opt.)		1 (Opt.)
	LPC	1		1
	I ² C	2		1
	SMBus	1		1
	CAN Bus	-		-
Audio	Interface	HD Audio		HD Audio
Ethernet	Controller	1 Intel® I210AT/IT		1 Intel® I210AT/IT
I/O	USB	2 USB 3.2, 8 USB 2.0		2 USB 3.2, 8 USB 2.0
	SATA	2 SATA 3.0		2 SATA 3.0
	SSD	-		1 4GB/8GB/16GB/32GB/64GB SSD (Opt.)
	eMMC	1 8GB/16GB/32GB/64GB eMMC (Opt.)		-
	DIO	8-bit DIO		6-bit DIO
	SD	Optional		Optional
TPM		-		dTPM or fTPM (Opt.)
Power		4.75V~20V, 5VSB, VCC-RTC (ATX mode) 4.75V~20V, VCC-RTC (AT mode)		4.75V~20V, 5VSB, VCC-RTC (ATX mode) 4.75V~20V, VCC-RTC (AT mode)
Operating Temperature		-40°C~85°C, 0°C~60°C		-40°C~85°C, 0°C~60°C

*Populated by default



Wide Temp

Atom

Wide Temp



AMD R1000

Model Name		BT9A3	GH9A3
Compliance		COM Express® R2.1 Mini, Type 10	
System	Processor	Intel® Atom® E3800	AMD® Ryzen™ Embedded R1000 Series
	Socket	BGA 1170	FP5
	Max. Speed	1.46~2.41GHz	up to 3.5GHz (Turbo)
	TDP	5W/7.5W/8W/10W	12W
	Cache	0.5M/1M/2M	1M
	BIOS	AMI SPI 64Mbit	SPI 64Mbit
Memory	Technology	Single Channel DDR3L 1333MHz	Single Channel DDR4 2400MHz
	Max. Capacity	2GB / 4GB	4GB / 8GB
	Socket	ECC Memory down	
Graphics	Interface	1 LVDS, 1 DDI	1 LVDS* <i>eDP</i> , 1 DDI
Expansion	PCIe	3 PCIe x1	
	SDIO	-	
	LPC	1	
	I ² C	1	
	SMBus	1	
	CAN Bus	-	
Audio	Interface	HD Audio	
Ethernet	Controller	1 Intel® I210AT/IT	1 Intel® I210
I/O	USB	1 USB 3.2, 8 USB 2.0	
	SATA	2 SATA 2.0	
	SSD	-	
	eMMC	1 4GB/8GB/16GB/32GB eMMC (Opt.)	
	DIO	8-bit DIO	
	SD	-	
TPM		-	
Power		4.75V~20V, 5VSB, VCC-RTC (ATX mode) 4.75V~20V, VCC-RTC (AT mode)	12V~20V, 5VSB, VCC-RTC (ATX mode) 12V~20V, VCC-RTC (AT mode)
Operating Temperature		-40°C~85°C, 0°C~60°C	

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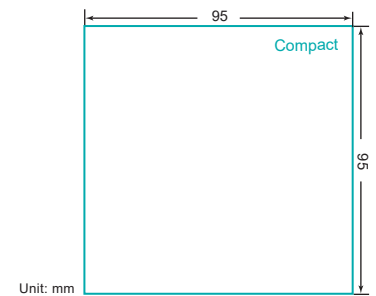
COM Express Compact

Reliable & Compact Solutions



Features

COM Express® Compact module is designed with computing capability and cost efficiency in a compact form factor with a footprint of 95 x 95 mm, making it the best Option for transportation and defense applications. DFI's Compact modules are available with COM Express® pin-out Type 2 and Type 6.



Wide Temp



ULT

Wide Temp



ULT

Wide Temp



ULT

Model Name		MTH968	RPP968	ADP968
Compliance		COM Express® R3.1 Compact, Type 6	COM Express® R3.1 Compact, Type 6	COM Express® R3.1 Compact, Type 6
System	Processor	14th Gen Intel® Core™	13th Gen Intel® Core™	12th Gen Intel® Core™
	Socket	FCBGA1744	FCBGA1744	FCBGA1744
	Max. Speed	1.1~2.7GHz	1.1~2.7GHz	1.0~1.8GHz
	TDP	15W/28W/45W	15W/28W/45W	15W/28W
	Cache	12M/24M	8M/10M/12M/18M/24M	8M/10M/12M/18M
	Chipset	-	-	-
BIOS		AMI BIOS	AMI BIOS	AMI BIOS
Memory	Technology	Dual Channel DDR5 5600MHz	Dual Channel DDR5 4800MHz	Dual Channel DDR4 3200MHz
	Max. Capacity	64GB	64GB	64GB
	Socket	2 SODIMM	2 SODIMM	2 SODIMM
Graphics	Interface	1VGA, 1LVDS* <i>eDP</i> , 3DDI	1VGA, 1LVDS* <i>eDP</i> , 3DDI	1VGA, 1LVDS* <i>eDP</i> , 3DDI
Expansion	PCIe	2 PCIe x4, 5 PCIe x1, 1 PCIe x8	2 PCIe x4, 5 PCIe x1	2 PCIe x4, 5 PCIe x1
	PCI	-	-	-
	LPC	-	-	-
	I ² C	1	1	1
	SMBus	1	1	1
	CAN Bus	-	-	-
Audio	Interface	HD Audio	HD Audio	HD Audio
Ethernet	Controller	1 Intel® I226, co-lay PCIe x1 (Opt.)	1 Intel® I226, co-lay PCIe x1 (Opt.)	1 Intel® I225, co-lay PCIe x1 (Opt.)
I/O	USB	4 USB 3.2, 8 USB 2.0	4 USB 3.2, 8 USB 2.0	4 USB 3.2 Gen2, 8 USB 2.0
	SATA	2 SATA 3.0	2 SATA 3.0	2 SATA 3.0
	IDE	-	-	-
	SSD	1 x 64GB/128GB/256GB/512GB/1024GB on board SSD (Opt.)	1 x 64GB/128GB/256GB/512GB/1024GB on board SSD (Opt.)	1 x 64GB/128GB/256GB/512GB/1024GB on board SSD (Opt.)
	eMMC	-	-	-
	DIO	8-bit DIO	8-bit DIO	8-bit DIO
	SD	-	-	-
TPM		Optional	Optional	Optional
iAMT		-	-	-
Power		8.5~20V, 5VSB, VCC-RTC (ATX mode) 8.5~12V, VCC-RTC (AT mode)	8.5~20V, 5VSB, VCC-RTC (ATX mode) 8.5~12V, VCC-RTC (AT mode)	8.5~20V, 5VSB, VCC-RTC (ATX mode) 8.5~20V, VCC-RTC (AT mode)
Operating Temperature		-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C

*Populated by default



Wide Temp

ULT

Wide Temp



ULT

Wide Temp



ULT

Model Name		TGU968	WL968	KU968
Compliance		COM Express® R3.0 Compact, Type 6	COM Express® R3.0 Compact, Type 6	COM Express® R2.1 Compact, Type 6
System	Processor	11th Gen Intel® Core™	8th Gen Intel® Core™	7th Gen Intel® Core™
	Socket	FCBGA 1449	FCBGA 1528	BGA 1356
	Max. Speed	1.5~4.4GHz	2.0~4.4GHz	2.2~3.9GHz
	TDP	15-28W	15W	15W
	Cache	4M~12M	2M/4M/6M/8M	2M/3M/4M
	Chipset	-	-	-
Memory	BIOS	AMI BIOS	AMI SPI 128Mbit	Insyde SPI 128Mbit
	Technology	Dual Channel DDR4 3200MHz	Dual Channel DDR4 2400MHz	Dual Channel DDR4 2133MHz
	Max. Capacity	64GB	64GB	4GB / 8GB / 16GB
Graphics	Socket	2 SODIMM	2 SODIMM	Memory down
	Interface	1 VGA*/DDI, 1 LVDS*/eDP, 3 DDI	1 VGA*/DDI, 1 LVDS*/eDP, 1 DDI	1 VGA*/DDI, 1 LVDS*/eDP, 1 DDI
Expansion	PCIe	8 PCIe x1 + 1 PCIe x4	6 PCIe x1 2 PCIe x1 + 1 PCIe x4 3 PCIe x1 + 2 PCIe x2	5 PCIe x1 4 PCIe x1 + 1 PCIe x4 3 PCIe x1 + 2 PCIe x2
	PCI	-	-	-
	LPC	-	1	1
	I ² C	1	1	1
	SMBus	1	1	1
	CAN Bus	-	-	-
Audio	Interface	HD Audio	HD Audio	HD Audio
Ethernet	Controller	1 Intel® I225	1 Intel® I219	1 Intel® I219
I/O	USB	4 USB 3.2, 8 USB 2.0	4 USB 3.2, 8 USB 2.0	4 USB 3.2, 8 USB 2.0
	SATA	2 SATA 3.0	Up to 3 SATA 3.0 (RAID) (Opt.)	3 SATA 3.0 (RAID)
	IDE	-	-	-
	SSD	1 x 64GB/128GB/256GB/512GB/1024GB on board SSD (Opt.)	-	-
	eMMC	-	eMMC 5.1 8GB/16GB/32GB/64GB/128GB (Opt.)	-
	DIO	8-bit DIO	8-bit DIO	8-bit DIO
	SD	-	-	-
TPM	Optional	Optional	Optional	
iAMT	-	iAMT 12.0 (Core i7/i5)	iAMT 11.0 (Core i7/i5)	
Power	8.5~20V, 5VSB, VCC-RTC (ATX mode) 8.5~20V, VCC-RTC (AT mode)	12V, 5VSB, VCC-RTC (ATX mode) 12V, VCC-RTC (AT mode)	12V, 5VSB, VCC-RTC (ATX mode) 12V, VCC-RTC (AT mode)	
Operating Temperature	-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C	

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Wide Temp

ULT

Wide Temp



Atom

Wide Temp



Atom

Model Name		SU968	AL968	BT968
Compliance		COM Express® R2.1 Compact, Type 6	COM Express® R2.1 Compact, Type 6	COM Express® R2.1 Compact, Type 6
System	Processor	6th Gen Intel® Core™	Intel® Atom® E3900 / Intel® Pentium® N4200	Intel® Atom® E3800
	Socket	BGA 1356	BGA 1296	BGA 1170
	Max. Speed	2~3.4GHz	1.8~2.5GHz	1.46~2.41GHz
	TDP	15W	6W/6.5W/9.5W/12W	5W/7.5W/8W/10W
	Cache	2M/3M/4M	2M	0.5M/1M/2M
	Chipset	-	-	-
Memory	BIOS	Insyde SPI 128Mbit	AMI SPI 128Mbit (supports UEFI boot only)	AMI SPI 64Mbit
	Technology	Dual Channel DDR3L 1600MHz	Dual Channel DDR3L 1600MHz	Dual/Single Channel DDR3L 1066/1333MHz
	Max. Capacity	16GB	8GB	4GB / 8GB
Graphics	Socket	2 SODIMM	2 SODIMM	1 or 2 SODIMM
	Interface	1 VGA*/DDI, 1 LVDS*/eDP, 1 DDI	1 VGA*/DDI, 1 LVDS*/eDP, 1 DDI	1 VGA, 1 LVDS*/DDI, 1 DDI
Expansion	PCIe	5 PCIe x1 4 PCIe x1 + 1 PCIe x4 3 PCIe x1 + 2 PCIe x2	4 PCIe x1	3 PCIe x1 or 1 PCIe x4
	PCI	-	-	-
	LPC	1	1	1
	I ² C	1	1	1
	SMBus	1	1	1
	CAN Bus	-	-	-
Audio	Interface	HD Audio	HD Audio	HD Audio
Ethernet	Controller	1 Intel® I219	1 Intel® I211 / 1 Intel® I210	1 Intel® I210
I/O	USB	4 USB 3.2, 8 USB 2.0	4 USB 3.2, 8 USB 2.0	1 USB 3.2, 8 USB 2.0
	SATA	3 SATA 3.0 (RAID)	2 SATA 3.0	2 SATA 2.0
	IDE	-	-	-
	SSD	-	-	-
	eMMC	-	1 x 8GB/16GB/32GB eMMC (Opt.)	1 x 4GB/8GB/16GB/32GB eMMC (Opt.)
	DIO	8-bit DIO	8-bit DIO	8-bit DIO
	SD	-	-	-
TPM	Optional	Optional	Optional	
iAMT	iAMT 11.0 (Core i7/i5)	-	-	
Power	12V, 5VSB, VCC-RTC (ATX mode) 12V, VCC-RTC (AT mode)	12V, 5VSB, VCC-RTC (ATX mode) 12V, VCC-RTC (AT mode)	12V, 5VSB, VCC-RTC (ATX mode) 12V, VCC-RTC (AT mode)	
Operating Temperature	-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C	-40°C~85°C, -20°C~70°C, 0°C~60°C	

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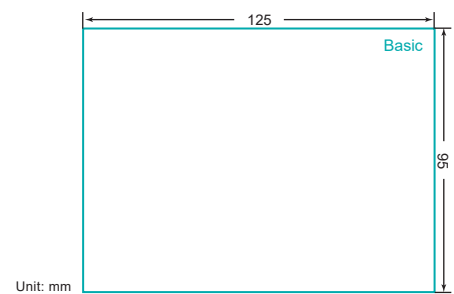
COM Express Basic

High-Performance & Cost-Effective Solutions



Features

COM Express® Basic module provides high-level processing performance and high-speed interfaces for a wide range of computing-demand applications such as medical, transportation, and industrial automation. DFI's Basic modules are compatible with COM Express® pin-out Type 2, Type 6 and Type 7.



Model Name	RBT970	ICD970	DV970
Compliance	COM Express® R3.1 Basic Type 7		
System	Processor	AMD® Ryzen™ Embedded V3000 Series processors	3rd Gen Intel® Xeon® Processor D-1700 Family
	Socket	FP7r2	FCLGA4189
	Max. Speed	1.9~3.5GHz	1.9~2.4GHz
	TDP	15W/45W	40W/50W/52W/59W/67W
	Cache	-	10M/15M
	Chipset	-	-
Memory	BIOS	AMI SPI 256Mbit	Insyde SPI 512Mbit
	Technology	Dual Channel DDR5 4800MHz	Dual Channel DDR4 2666/2933MHz
	Max. Capacity	64GB	64GB
Graphics	Socket	2 SODIMM	2 SODIMM
	Interface	-	-
Expansion	PCIe	1 PCIe x14 (Gen 4)	2 PCIe x8 (Gen3), 1 PCIe x16 (Gen4)
	LPC	1	1
	I ² C	1	1
	SMBus	1	1
	CAN Bus	-	-
	Audio	Interface	-
I/O	Ethernet	Controller	2 10G Ethernet, 1 2.5G Ethernet
	USB	4 USB 3.2, 4 USB 2.0	4 USB 3.2, 4 USB 2.0
	SATA	2 SATA 3.0 (up to 6Gb/s)	2 SATA 3.0 (up to 6Gb/s)
	IDE	-	-
	SSD	-	-
	eMMC	-	eMMC 5.1 16GB (Opt.)
	DIO	1 x 8-bit DIO (Default 4 inputs and 4 outputs)	1 x 8-bit DIO (Default 4 inputs and 4 outputs)
TPM	Optional	Optional	
iAMT	-	-	
Power	12V, 5VSB, VCC-RTC (ATX mode) 12V, VCC-RTC (AT mode)	12V, 5VSB, VCC-RTC (ATX mode) 12V, VCC-RTC (AT mode)	12V, 5VSB, VCC-RTC (ATX mode) 12V, VCC-RTC (AT mode)
	Operating Temperature	-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C

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Wide Temp

RM590E/QM580E/HM570E

Wide Temp

CM246/QM370/HM370

Wide Temp

CM246/QM370/HM370

Model Name		TGH960	CH960-CM246/QM370/HM370	CH961-CM246/QM370/HM370
Compliance		COM Express® R3.0 Basic Type 6	COM Express® R2.1 Basic Type 6	COM Express® R2.1 Basic Type 6
System	Processor	11th Gen Intel® Core™	9th/8th Gen Intel® Core™	9th/8th Gen Intel® Core™
	Socket	BGA 1787	BGA 1440	BGA 1440
	Max. Speed	3.1~4.7GHz	2.5~4.4GHz	2.5~4.5GHz
	TDP	25W/35W/45W	45W	45W
	Cache	8M/12M/24M	2M/4M/6M/8M/9M/12M	2M/4M/6M/8M/9M/12M
	Chipset	Intel® RM590E/QM580E/HM570E	Intel® CM246/QM370/HM370	Intel® CM246/QM370/HM370
Memory	BIOS	AMI SPI 256Mbit	AMI SPI 128Mbit	AMI SPI 128Mbit
	Technology	Dual Channel DDR4 3200MHz ECC support	Dual Channel DDR4 2666MHz	Dual Channel DDR4 2666MHz
	Max. Capacity	128GB	64GB	96GB
Graphics	Socket	4 SODIMM	2 SODIMM	4 SODIMM
	Interface	1 VGA, 1 LVDS*/eDP, 3 DDI	1 VGA*/DDI, 1 LVDS*/eDP, 2 DDI	1 VGA*/DDI, 1 LVDS*/eDP, 2 DDI
Expansion	PCIe	1 PCIe x16 (Gen 4), 8 PCIe x1 (Gen 3)	1 PCIe x16 / 2 x PCIe x8 / 1 PCIe x8 + 2 PCIe x4	1 PCIe x16, 8 PCIe x1
	LPC	1	1	1
	I ² C	1	1	1
	SMBus	1	1	1
	CAN Bus	-	-	-
Audio	Interface	HD Audio	HD Audio	HD Audio
Ethernet	Controller	1 Intel® I225 series (10/100/1000Mbps/2.5G)	1 Intel® I219	1 Intel® I219
I/O	USB	4 USB 3.2 Gen2, 8 USB 2.0	4 USB 3.2, 8 USB 2.0	4 USB 3.2, 8 USB 2.0
	SATA	4 SATA 3.0 (up to 6Gb/s) support RAID 0/1/5/10	4 SATA 3.0 (RAID in CM246 & QM370)	4 SATA 3.0 (up to 6Gb/s) support RAID 0/1/5/10
	IDE	-	-	-
	SSD	(Opt.) NVMe SSD: PCIe x4 Gen4, 64GB~1TB	-	-
	eMMC	-	-	-
	DIO	1 x 8-bit DIO (Default 4 inputs and 4 outputs)	1 x 8-bit DIO (Default 4 inputs and 4 outputs)	1 x 8-bit DIO (Default 4 inputs and 4 outputs)
TPM	Optional	Optional	Optional	
iAMT	iAMT 12.0 (Core i7/i5 in RM590E & QM580E)	iAMT 12.0 (Core i7/i5 in CM246 & QM370)	iAMT 12.0 (Core i7/i5 in CM246 & QM370)	
Power	8.5V~20V, 5VSB, VCC-RTC (ATX mode) 8.5V~20V, VCC-RTC (AT mode)	12V, 5VSB, VCC-RTC (ATX mode), 12V, VCC-RTC (AT mode)	8.5V~20V, 5VSB, VCC-RTC (ATX mode) 8.5V~20V, VCC-RTC (AT mode)	
Operating Temperature	-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C	

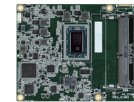
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Wide Temp

CM236/QM170

Wide Temp



AMD

Model Name		SH960MD-CM236/QM170	GH960
Compliance		COM Express® R2.1 Basic, Type 6	COM Express® R3.0 Basic, Type 6
System	Processor	6th Gen Intel® Core™	AMD® Ryzen™ V1000/R1000 Embedded Processors
	Socket	BGA 1440	FP5 BGA
	Max. Speed	1.9~3.5GHz	3.2~3.8GHz
	TDP	25W/35W/45W	12-25W/35-54W
	Cache	2M/3M/6M/8M	1M/2M
	Chipset	Intel® CM236/QM170	-
Memory	BIOS	Insyde SPI 128Mbit	Insyde SPI 64Mbit
	Technology	Dual Channel DDR4 2400MHz	Dual Channel DDR4 up to 2400/3200MHz
	Max. Capacity	8GB / 16GB	32GB
Graphics	Socket	Memory down	2 SODIMM
	Interface	1 VGA*/DDI, 1 LVDS*/eDP, 2 DDI	1 VGA*/DDI, 1 LVDS*/eDP, 2 DDI
Expansion	PCIe	1 PCIe x16 / 2 PCIe x8, 8 PCIe x1	1 PCIe x8, 6 PCIe x1 / 2 PCIe x2 / 1 PCIe x4
	LPC	1	1
	I ² C	1	1
	SMBus	1	1
	CAN Bus	-	-
Audio	Interface	HD Audio	HD Audio
Ethernet	Controller	1 Intel® I210	1 Intel® I210
I/O	USB	4 USB 3.2, 8 USB 2.0	4 USB 3.2, 8 USB 2.0
	SATA	4 SATA 3.0 (up to 6Gb/s) support RAID 0/1/5/10	4 SATA 3.0 (up to 6Gb/s) support RAID 0/1/5/10
	IDE	-	-
	SSD	-	-
	eMMC	-	-
	DIO	8-bit DIO	8-bit DIO
TPM	Optional	TPM 1.2/2.0 (Opt.)	
iAMT	iAMT 11.0 PCIe	-	
Power	12V, 5VSB, VCC-RTC (ATX mode) 12V, VCC-RTC (AT mode)	12V, 5VSB, VCC-RTC (ATX mode), 12V, VCC-RTC (AT mode)	
Operating Temperature	-40°C~85°C, 0°C~60°C	-40°C~85°C, 0°C~60°C	

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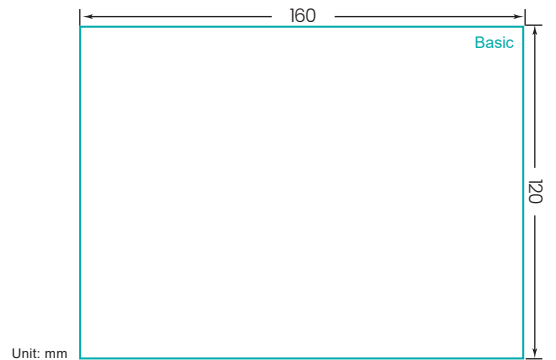
COM HPC

Computer on Module High Performance Computing



Features

Supports high-performance multi-core processors, possesses high-performance edge computing capabilities, and offers flexible expandability, meeting the requirements of various industrial applications. It also supports multiple high-speed interfaces suitable for data-intensive and compute-intensive applications.



Wide Temp

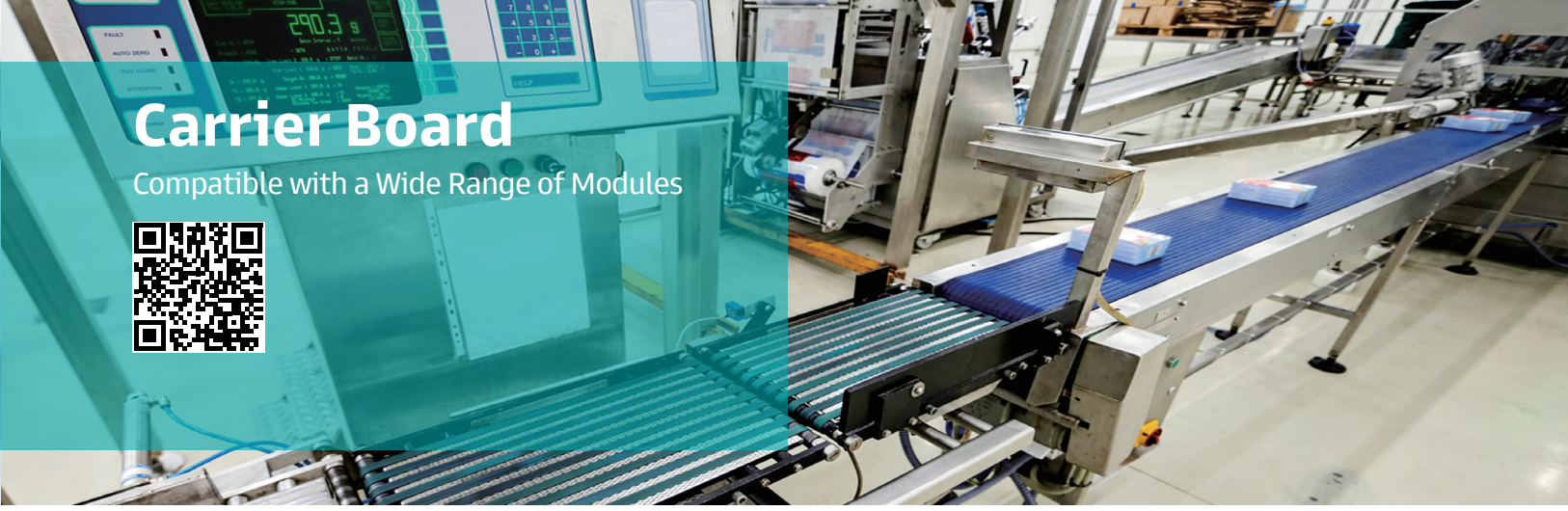
R680E/Q670E/H610E

Model Name		RPS9HC-R680E/Q670E/H610E
Compliance		COM HPC® R1.15, Client Size C
System	Processor	13th Gen Intel® Core™
	Socket	LGA 1700
	Max. Speed	3.3~5.2GHz
	TDP	35W/60W/65W
	Cache	12M/20M/24M/30M/36M
	Chipset	Intel® R680E/Q670E/H610E
Memory	BIOS	AMI SPI 256Mbit
	Technology	Dual Channel DDR5 (ECC support by R680 with i7 and i5)
	Max. Capacity	128GB
Graphics	Socket	4 SODIMM
	Interface	1 eDP, 3 DDI
Expansion	PCIe	1 x PCIe x16 (Gen5) 4 x PCIe x4 (Gen4) 2 x PCIe x4 (Gen3) 2 x PCIe x1 (Gen3)
	PCI	-
	LPC	-
	I ² C	1
	SMBus	1
	CAN Bus	-
Audio	Interface	HD Audio
I/O	Ethernet Controller	2 Intel® I226
	USB	4 USB 3.2 Gen2, 8 USB 2.0
	SATA	2 SATA 3.0 (up to 6Gb/s)
	DIO	12 bit in/out
TPM		TPM 2.0 (Opt.)
Power		12V, 5VSB, VCC-RTC (ATX mode) 12V, VCC-RTC (AT mode)
	Operating Temperature	0°C~60°C

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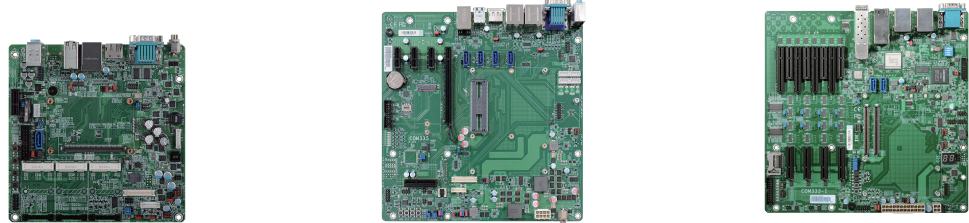
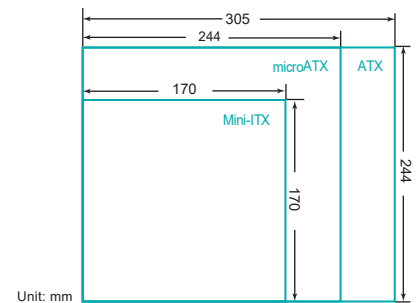
Carrier Board

Compatible with a Wide Range of Modules



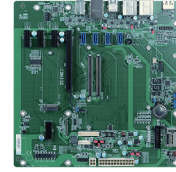
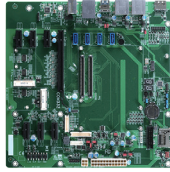
Features

Our carrier board (also known as base board or evaluation board) offers a flexible engineering development environment for COM Express Type 10, Type 7, Type 6, Type 2, Qseven and SMARC to help our customers minimize installation requirements while reducing design time and cost.



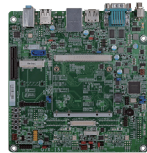
Model Name	COM100-B	COM335	COM333-I
Compliance	COM Express® R2.1, Type 10	COM Express® R3.1, Type 6, Type 10	COM Express® R3.0, Type 7
Form Factor	Mini-ITX (170 x 170 mm)	microATX (244 x 244 mm)	microATX (244 x 244 mm)
Graphics	Connector	1 LVDS, 1 DP	1 LVDS*/eDP, 1 eDP*/LVDS
	PCIe, PCI	1 PCIe x1	1 PCIe x16, 1 PCIe x4, 3 PCIe x1
Expansion	Mini PCIe, M.2	3 Mini PCIe	8 PCIe x4 / 4 PCIe x8
	SIM	1	-
Audio	Audio Codec	Realtek ALC886	Realtek ALC888S-VD2-GR
	Ethernet (GbE)	1	1
Rear I/O	Serial	2 RS-232	1 RS-232
	USB	2 USB 3.2, 4 USB 2.0	3 USB 3.2, 4 USB 2.0
	Display	1 DP	3 DP
	Audio	Mic-in, Line-in, Line-out	Min-in, Line-in, Line-out
	PS/2	-	-
Internal I/O	Serial	1 (TX/RX)	1 (TX/RX)
	USB	-	-
	Display	1 LVDS	1 VGA, 1 LVDS, 1 eDP
	Audio	Front Audio, S/PDIF	1 Audio (Line-out/Mic-in), 1 S/PDIF
	SATA	1 SATA 3.0	4 SATA 3.0
	DIO	8-bit DIO	8-bit DIO
	LPC	1	1
	SMBus	1	1
Power	5~19V DC-in	4-pin ATX 12V, 24-pin ATX	4-pin ATX 12V, 24-pin ATX
Operating Temperature	0°C~60°C	0°C~60°C	0°C~60°C

*Populated by default



Model Name		COM332-B(R.A)	COM332-B(R.B1)
Compliance		COM Express® R2.1, Type 6	COM Express® R2.1, Type 6
Form Factor		microATX (244 x 244 mm)	microATX (244 x 244 mm)
Graphics	Connector	1 VGA, 3 DP, 1 LVDS*/eDP, 1 eDP*/LVDS	1 VGA, 3 DP, 1 LVDS*/eDP, 1 eDP*/LVDS
Expansion	PCIe, PCI	1 PCIe x16, 6 PCIe x1	1 PCIe x16, 4 PCIe x1
	Mini PCIe, M.2	2 Full-size Mini PCIe	1 M.2 M Key 2280
	SIM	-	-
Audio	Audio Codec	Realtek ALC888S-VD2-GR	Realtek ALC888S-VD2-GR
Rear I/O	Ethernet (GbE)	1	1
	Serial	-	-
	USB	4 USB 3.2, 4 USB 2.0	4 USB 3.2, 4 USB 2.0
	Display	3 DP	3 DP
	Audio	Mic-in, Line-in, Line-out	Mic-in, Line-in, Line-out
	PS/2	-	-
Internal I/O	Serial	2 (TX/RX)	2 (TX/RX)
	USB	-	-
	Display	1 VGA, 1 LVDS, 1 eDP	1 VGA, 1 LVDS, 1 eDP
	Audio	Front Audio, S/PDIF	Front Audio, S/PDIF
	SATA	4 SATA 3.0	4 SATA 3.0
	DIO	8-bit DIO	8-bit DIO
	LPC	1	1
	SMBus	1	1
	I ² C	-	-
	Power	4-pin ATX 12V, 24-pin ATX	4-pin ATX 12V, 24-pin ATX
Operating Temperature		0°C~60°C	0°C~60°C

*Populated by default



Model Name		Q7X-151(R.A)	Q7X-151(R.D1)	Q7A-551
Compliance		BT700	AL700 / AL701 / BT701	FS700
Form Factor		Mini-ITX (170 x 170 mm)	Mini-ITX (170 x 170 mm)	Proprietary (190 x 102 mm)
Graphics	Connector	1 LVDS, 1 DP	1 LVDS, 2 DP, 1 eDP	1 HDMI, 1 LVDS
Expansion	PCIe, PCI	1 PCIe x4	2 PCIe x1	-
	Mini PCIe, M.2	-	2 Mini PCIe	1 Mini PCIe
	SIM	-	-	1
Audio	Audio Codec	Realtek ALC886	Realtek ALC886	I2S
Rear I/O	Ethernet (GbE)	1	1	1
	Serial	2 RS-232	2 RS-232	2 RS-232
	USB	1 USB 3.2, 2 USB 2.0	3 USB 3.2, 6 USB 2.0	2 USB 2.0, 1 USB Client
	Display	1 DP	1 DP	1 HDMI
	Audio	Mic-in, Line-in, Line-out	Mic-in, Line-in, Line-out	Line-out / Mic-in
	PS/2	-	-	-
Internal I/O	Serial	1 (TX/RX)	1 (TX/RX)	1 RS-232/422/485
	USB	4 USB 2.0 (Optional)	2 USB 2.0 (Optional)	-
	Display	1 LVDS	1 LVDS	1 LVDS
	Audio	-	-	2 1W audio amplifier connectors (left and right sides)
	SATA	1 SATA 3.0, 1 mSATA	2 SATA 3.0	-
	DIO	-	-	12-bit DIO
	LPC	1	1	-
	SMBus	1	1	-
	I ² C	1	1	-
	CANBus	1	1	1
Power	12V DC-in	12V DC-in	12~36V DC-in	
Operating Temperature		0°C~60°C	0°C~60°C	0°C~60°C

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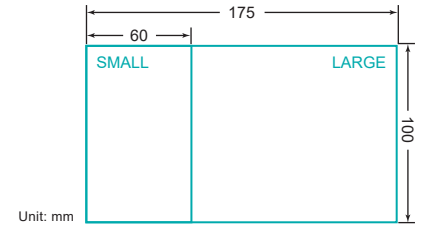
SDM

Compact & Smart Retail Signage Solutions



Features

Intel® Smart Display Module is for next generation commercial AIO displays and visual IoT devices. Intel® SDM provides the primary compute building block and requires an interface board on the displays or host system to complete platform implementation and provide standard end user physical interfaces.



Large Size: 175mm x 100mm
Small Size: 60mm x 100mm



Model Name		SDML-WL
Compliance		SDM Large
System	Processor	8th Gen Intel® Core™
	Socket	FCBGA 1528
	Max. Speed	2.0~4.4GHz
	TDP	15W
	Cache	2M/4M/6M/8M
Memory	Chipset	-
	BIOS	AMI Winbond SPI 128Mbit
	Technology	Dual Channel DDR4 2400MHz
Graphics	Max. Capacity	32GB
	Socket	2 SODIMM
Expansion	Interface	1 DP, 2 HDMI
	PCIe	1 PCIe x1 for docking, 1 PCIe x4 for M.2 M Key, 1 PCIe x1 for M.2 B Key, 1 PCIe x1 for M.2 E Key
	PCI	-
	LPC	-
	I ² C	1 I ² C master, 1 I ² C slaver (for docking)
	SMBus	-
Audio	CAN Bus	-
	Interface	Realtek ALC262-VC2-GR
I/O	Controller	1 Intel® I219
	USB	4 USB 3.2 (Type A), 1 USB 3.2 (Type C)
	SATA	-
	IDE	-
	SSD	-
	eMMC	-
	DIO	-
SD	-	
TPM		Optional
iAMT		iAMT 12.0 (Core i7/i5)
Power		12V DC-in
Operating Temperature		0°C~60°C

*Populated by default



Headquarters

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